Product End-of-Life Disassembly Instructions

Product Category: Other Products
Marketing Name / Model [List multiple models if applicable.]
HP 2.8kVA 120V 12out NA/JP mPDU / D9N43A
HP 4.9kVA 208V 12out NA/JP mPDU / D9N44A
HP 3.6kVA 230V 12out WW mPDU / D9N46A

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	3
Batteries	All types including standard alkaline and lithium coin or button style batteries	0
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords	Depending on Model number	1
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0

Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Philips Screw Driver	#2
Torx Head Screw Driver	T10
Socket Wrench	M3
Socket Wrench	M4

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Removal of top cover with T10 torx screw driver of unit.
2. Cut the internal wiring.
3. Removal of SCOB module with M3 and M4 socket wrench.
4. Removal of SPS+ICM PCBA with Philips screw Driver.
5. Removal of power cord with T10 torx screw driver.
6. Removal of breaker with Philips screw Driver.
7.
8.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

(1) The Component location of HP Glandore PDU 1U unit

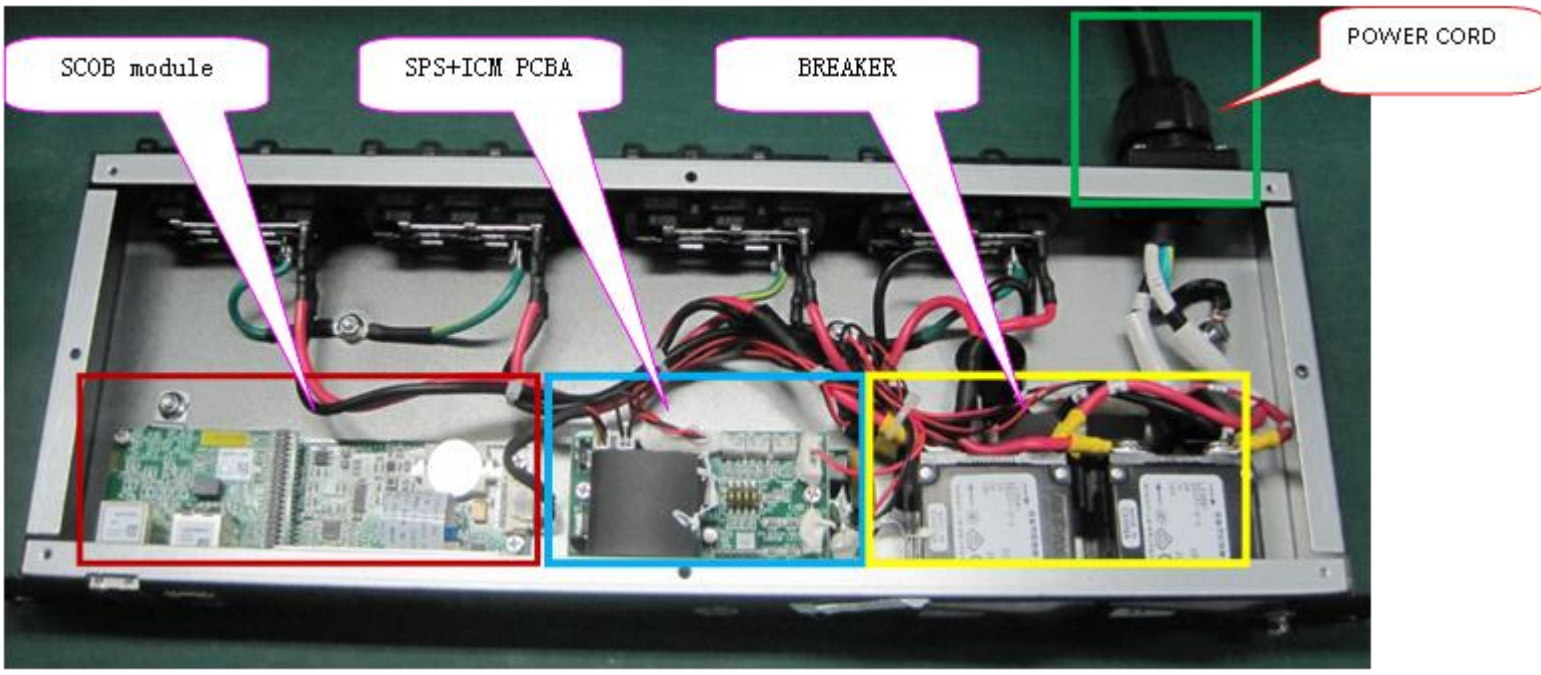
(2) SCOB module disassembly

(3) PCBA disassembly

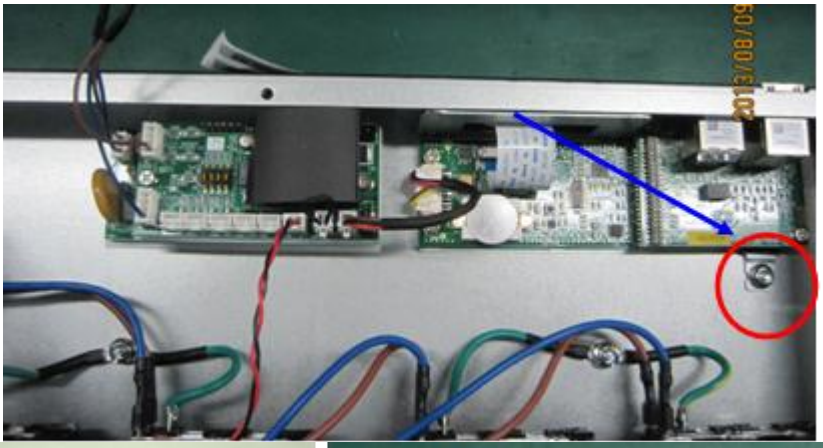
(4) Power Cord disassembly

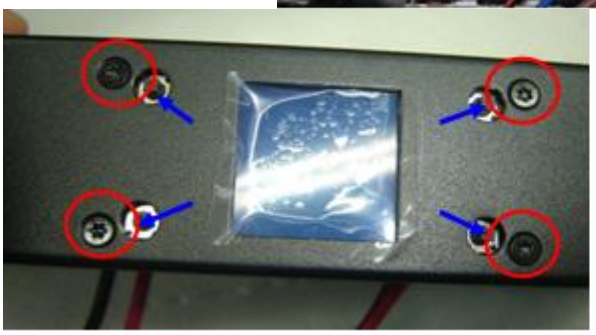
(5) Breaker disassembly

(1) The Component location of HP Glandore PDU 1U unit

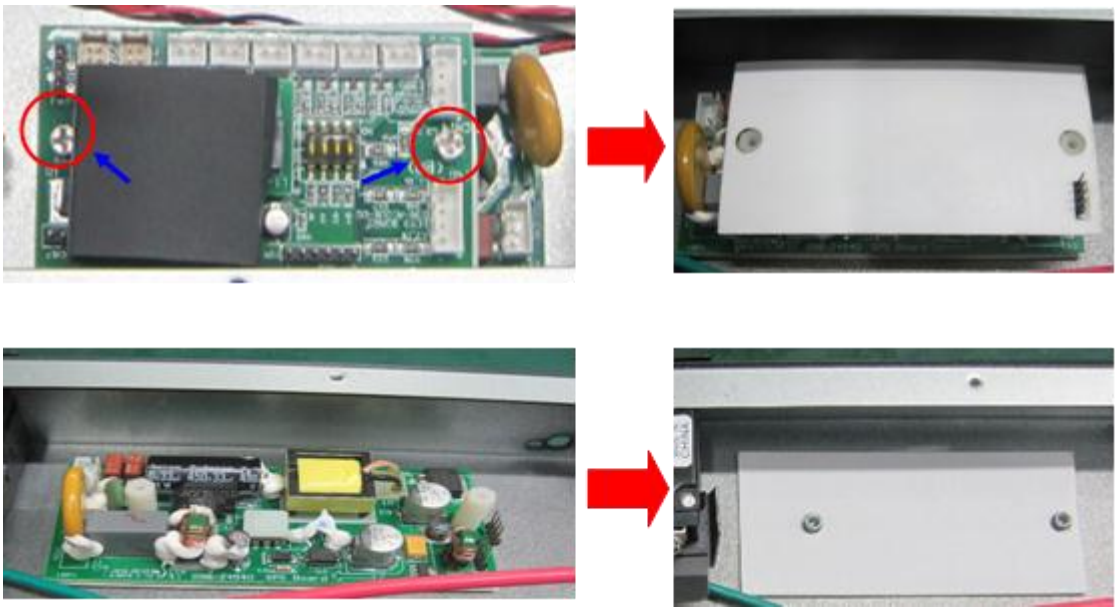


(2) SCOB module disassembly





(3) PCBA disassembly



(4) Power Cord disassembly

(5) Breaker disassembly